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# High-Performance Wi-Fi

## **Solutions for Customer Premise Equipment Applications**

Microsemi has a growing portfolio of world-class RF products for Wi-Fi 802.11 a/b/g/n/ac applications. Microsemi Wi-Fi solutions include high-performance front-end modules (FEMs), power amplifiers (PAs), and low-noise amplifiers (LNAs). Featuring highly integrated monolithic RFIC design, Microsemi's latest generation of midpowered FEMs is optimized for long-packet EVM performance and high efficiency, and is ideally suited for client-based access points, gateways, and 4K media streaming platforms.

Microsemi's 5-GHz/2-GHz FEM is the industry's first dual-band solution, integrating all functions for PA, LNA, switches, band-edge filter, diplexer, harmonic and out-of-band rejection, and impedance matching in a single monolithic die. Low current consumption, 3.3-volt supply, and 4mm-by-3mm compact size are ideal for smart television and OTT media platforms.

Microsemi's family of high-linearity power amplifiers features the latest in 2.4-GHz and 5-GHz amplifiers. With market-leading current consumption, Microsemi solutions deliver the high power required in newer 802.11ac systems, critical for thermal management of today's newer 4×4 and 8×8 MIMO configurations.



## **High-Linearity 2.4-GHz Amplifiers**

Part Number	Freq (GHz)	802.11 Standard	Description	Gain (dB)	Linear Po (dBm)	EVM (%)	Vcc (V)	Current @ Po (mA)	Package (mm)
LX5511	2.3-2.5	n	PA + PDET	26.0	20	3.0	3.3	170	QFN-16, 3×3×0.9
LX5535	2.4-2.5	n	PA + PDET	32.0	24.5	3.0	3.3–5	260	QFN-16, 3×3×0.9
LX5518	2.4-2.5	n	PA + PDET	30.0	26	3.0	3.3–5	390	QFN-16, 3×3×0.9
<b>NEW</b> LX5533	0405	n	DA Filtoring DDFT	30.0	26	3.0 5	440	QFN-16, 3×3×0.9	
INEVV LASSSS	2.4–2.5	ac	PA, Filtering, PDET	30.0	24 1.8	5	380		

### **High-Linearity 5-GHz Amplifiers**

Part Number	Freq (GHz)	802.11 Standard	Description	Gain (dB)	Linear Po (dBm)	EVM (%)	Vcc (V)	Current @ Po (mA)	Package (mm)
LX5530	4.9-5.9	n	PA + PDET	28.0	22	3.0	3.3-5	360	QFN-16, 3×3×0.9
1.7/2.201	5.15–5.85	n	DA Filtoring DDFT	22.0	25	3.0	5	350	OFN 00 440 0
LX5531	5.15-5.65	ac	PA, Filtering, PDET	33.0	23	1.8	5	290	QFN-20, 4×4×0.9
NEW LYEEOO	E 1 E E 0 E	n	DA Filtoring DDFT	32.0	0 25 3.0 5 400 23 1.8 5 340	5	400	OFN 00 4.4.0.0	
<b>NEW</b> LX5532	5.15–5.85	ac	PA, Filtering, PDET	32.0		340	QFN-20, 4×4×0.9		

#### **Low-Noise Amplifiers**

Part Number	Freq (GHz)	802.11 Standard	Description	Gain (dB)	Noise Figure (dB)	IIP3 (dBm)	Current @ Po (mA)	Vcc (V)	Package (mm)
LX5561	2.4-2.5	b/g/n/ac	LNA	13	1.5	6.5	10.5	3.3	QFN-12, 2×2×0.5
LX5560	4.9-6.0	a/n/ac	LNA	12	1.7	6	9.5	3.3	QFN-12, 2×2×0.5
LX5563	2.4-2.5	b/g/n/ac	LNA + Bypass	14	1.3	7.5	9	3.3	DFN-6, 1.5×1.5×0.5
LX5575	5.15-5.85	a/n/ac	LNA + Bypass	12	1.7	12	9	3.3–5	QFN-16, 2.5×2.5×0.45

#### **Dual-Band Front-End Modules**

Part Number	Freq (GHz)	802.11 Standard	Description	Gain (dB)	Linear Po (dBm)	EVM (%)	Vcc (V)	Current @ Po (mA)	Package (mm)
	2.4–2.5	n	Dual-Band	00	18	3.0	0.0	210	QFN-28, 4×3×0.9
AJEIA I VEEO		ac		30	16 1.8	1.8	3.3	190	
<b>NEW</b> LX5591	5.15–5.85	n	PA + PDET + LNA with Bypass + SPDT	27	18	3.0	0.0	260	
		ac		27	16	16 1.8	3.3	230	

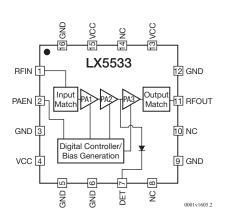


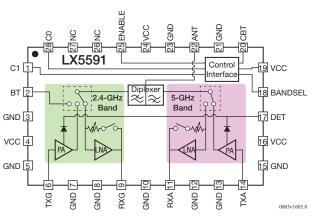
# High-Performance Wi-Fi

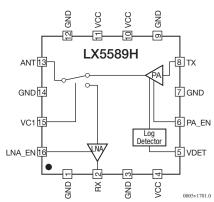
# **Solutions for Customer Premise Equipment Applications**

### Single-Band, High-Linearity Front-End Modules

Part Number	Freq (GHz)	802.11 Standard	Description	Gain (dB)	Linear Po (dBm)	EVM (%)	Vcc (V)	Current @ Po (mA)	Package (mm)
LX5551	2.4-2.5	n	PA + SPDT + PDET	27	18	3.0	3.3	140	QFN-16, 3×3×0.9
NEW LYFFOAA	0.4.0.5	n	PA + Log DET + LNA with	30	19	3.0	3.3	220	OFN 10 0 0 0 0
<b>NEW</b> LX5584A	2.4–2.5	ac	bypass + SP3T	30	18	1.8	3.3	200	QFN-16, 3×3×0.9
<b>NEW</b> LX5584B	2.4–2.5	n	PA + Log DET + LNA with	33	21	3.0	5.0	260	OFN 40 0 0 0 0
NEW LASSO4B	2.4-2.5	ac	Bypass + SP3T	33	20	3.0 5.0 3.0 5.0 1.8 5.0 3.0 3.3 1.8 3.3	240	QFN-16, 3×3×0.9	
<b>NEW</b> LX5584H	2.4–2.5	n	PA + Log DET + LNA with Bypass + SP3T	33	21	3.0	5.0	260	QFN-16, 2.5×2.5×0.9
INEW LASSOAN	2.4-2.5	ac			20	1.8	5.0	240	
LX5586	5.15–5.85	n	PA + PDET + LNA with Bypass + SPDT	27	17.0	17.0 3.0 3.3 200	QFN-16, 2.5×2.5×0.4		
LAJJOU	3.13-3.03	ac		<u> </u>	16.0	1.8	3.3	185	Q111-10, Z.UXZ.UXU.4
LX5586A	5.15–5.85	n	PA + PDET + LNA with	27	17.5	3.0	3.3	200	QFN-16, 2.5×2.5×0.45
LASSOCA	5.15-5.65	ac	Bypass + SPDT	21	16.5	1.8	3.3	185	QFN-10, 2.0x2.0x0.40
LX5586H	5.15–5.85	n	PA + PDET + LNA with	27	20	3.0	5.0	230	OEN 16 2 5 2 5 2 0 15
LAUUOUH	5.15-5.65	ac	Bypass + SPDT	21	19	1.8	5.0	210	QFN-16, 2.5×2.5×0.45
<b>NEW</b> LX5589A	5.15–5.85	n PA + Log DET + LNA with	30	18	3.0	3.3	210	OFN 10 0 5 0 5 0 0	
NEW LASSIBA	3.13-3.03	ac	Bypass + SPDT	30	17	1.8	3.3	190	QFN-16, 2.5×2.5×0.9
NEW I VEEDOLI	5.15–5.85	n	PA + Log DET + LNA with	32	22	3.0	5.0	250	QFN-16, 2.5×2.5×0.9
<b>NEW</b> LX5589H	0.10-0.00	ac	Bypass + SPDT	52	20	1.8	5.0	230	
<b>NEW</b> LX5589B	5 15 5 05	n	PA + Log DET + LNA with	32	22	3.0	5.0	250	QFN-16, 3×3×0.9
INENN LY330AB	5.15-5.85	5.15–5.85 ac	Bypass + SPDT	32	20	1.8	5.0	230	









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